





# **High Power Surface Mount Fuse** CM2822H Series



# **Applications:**

- Server Systems
- Routers and switches
- Telecom DC/DC Power

# **Clearing Time Characteristics:**

W of Current Boting	Clearing Time at 25°C	
% of Current Rating	Min.	Max.
100%	4 hours	
250%		60 seconds

### **Agency Approval:**

Recognized Under the Components Program of Underwriters Laboratories. File Number: E507943.

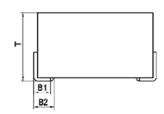
### Features:

- High safety with ceramic body and special arcextinguishing filler
- High interrupting current ratings for high power input protection
- Up to 125A with very low profile
- High reliability for long time operation
- Halogen free, RoHS compliant and 100% lead-free

## **Shape and Dimensions:**

Unit	Inch	mm
L	0.287 ± 0.012	$7.3 \pm 0.3$
w	0.228 ± 0.008	5.8 ± 0.2
Т	0.165 ± 0.008	4.2 ± 0.2
B1	0.051 ± 0.012	1.3 ± 0.3
B2	0.063 ± 0.012	1.6 ± 0.3





# **Ordering Information:**

Part Number	Current Rating (A)	Voltage Rating (VDC)	Interrupting Rating	Nominal DCR (mΩ)	Nominal I <sup>2</sup> t (A <sup>2</sup> s)
CM2822H20A0T	20	125	300A @ 125VDC 1000A @ 75VDC 1500A @ 48VDC	2.10	120
CM2822H30A0T	30			1.35	270
CM2822H40A0T	40			1.05	400
CM2822H50A0T	50			0.85	600
CM2822H60A0T	60	75	75 1000A @ 75VDC 1500A @ 48VDC	0.74	900
CM2822H70A0T	70			0.61	1400
CM2822H80A0T	80			0.53	2000
CM2822H90A0T	90			0.48	2400
CM2822H100AT	100			0.44	3600
CM2822H125AT	125			0.38	6000

- 1. Measured at ≤10% rated current and 25 □ ambient
- 2. Melting I2t at 10X In
- 3. Time Constant of Interrupting Test less than 0.1ms

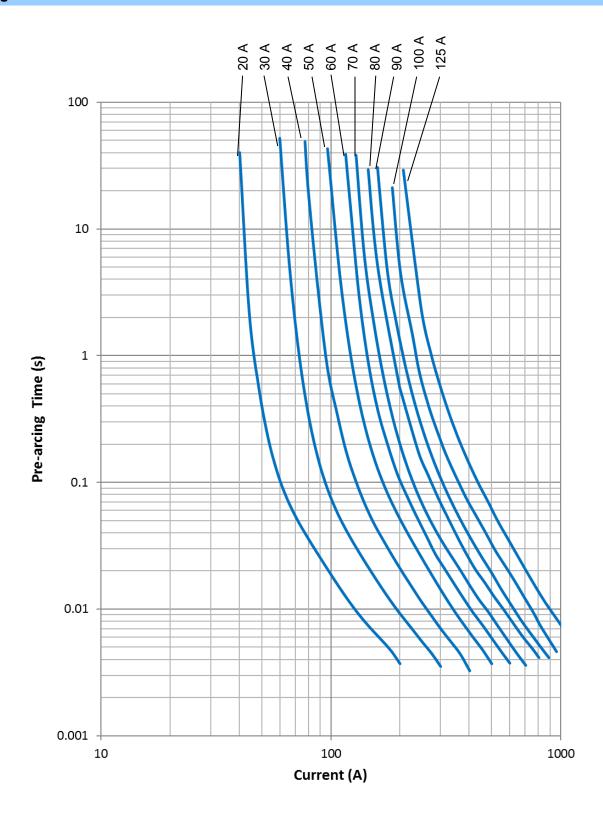






# **High Power Surface Mount Fuse** H Series

# **Clearing Time vs. Current Curves:**

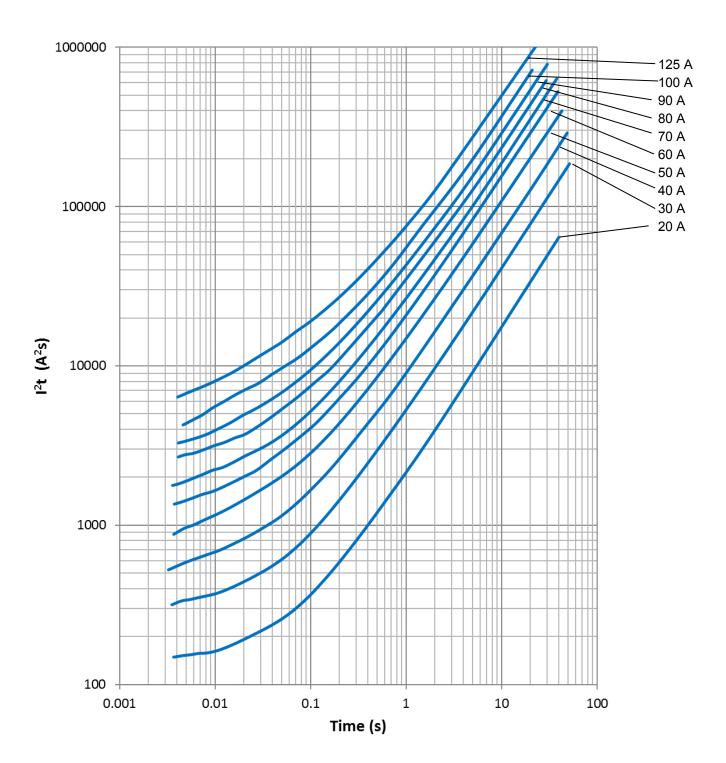






# **High Power Surface Mount Fuse H Series**

# Average I<sup>2</sup>t vs. t Curves:











# **High Power Surface Mount Fuse H Series**

#### **Product Identification:**

<u>CM 2822 H 20A0 T</u>

(1) (2) (3) (4) (5)

(1) Product Code: CM-Commercial Molding Fuse

(2) Size code: L x W (inch): the first two digits - L (length), the last two digits - W (width)

(3) Series code: H

(4) Current rating code: e.g. 20A0: 20.0A

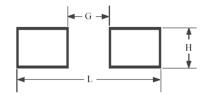
(5) Package code: T - Tape & Reel, B - Bulk

Marking: Top Line: AEM Logo; CMH: CM2822H Series

Bottom Line: Current Rating Code

#### **Recommended Land Pattern:**

Chip Size	2822 (7358)
L Inch (mm)	0.386 (9.8)
G Inch (mm)	0.173 (4.4)
H Inch (mm)	0.228 (5.8)

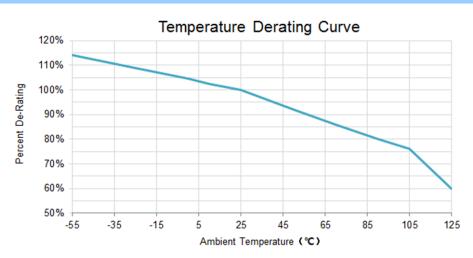


## Packaging:

Chip Size	Parts on 13 inch (330 mm) Reel
2822	1000pcs

# **Fuse Selection and Temperature De-rating Guideline:**

The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25 °C, the fuse shall be "de-rated" according to the de-rating curve.







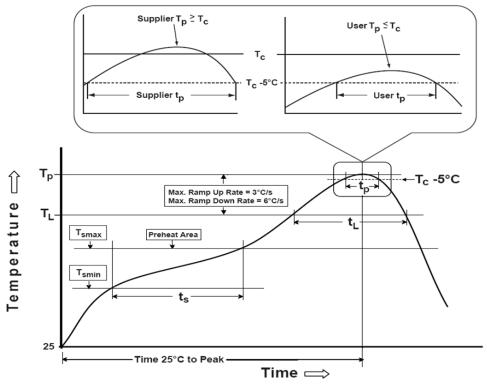




# **High Power Surface Mount Fuse H** Series

## **Recommended Temperature Profile for Reflow Soldering:**

Profile Feature	Pb-Free Assembly
Preheat/Soak	
Temperature Min (T <sub>smin</sub> )	150°C
Temperature Max(T <sub>smax</sub> )	200°C
Time( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60~120 seconds
Ramp-uprate (T <sub>L</sub> to T <sub>p</sub> )	3°C/second max.
Liquidous temperature(T <sub>L</sub> )	217°C
Time(t <sub>L</sub> ) maintained above T <sub>L</sub>	60~150 seconds
Peak package body temperature (Tp)	260°C
Time (t <sub>p</sub> )*within 5°C of the specified classification temperature (T <sub>c</sub> )	30 seconds *
Ramp-down rate (Tp to TL)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.
* Tolerance for peak profile temperature (T <sub>p</sub> ) is defined as a supplier r	minimum and a user maximum



Recommended conditions for hand soldering:

- 1. Appropriate temperature (max.) of soldering iron tip/soldering time (max.): 280°C /10 s or 350°C / 3 s
- 2. Using hot air rework station with tip that can melt the solder on both terminations at the same time is strongly recommended. Do not directly contact the chip termination with the tip of soldering iron.

### Storage:

The maximum ambient temperature shall not exceed 35°C . Storage temperatures higher than 35°C could result in the deformation of packaging materials.

The maximum relative humidity recommended for storage is 75%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components.

The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

MSL=1





## **Disclaimer**

Specifications are subject to change without notice. AEM products are designed for specific applications and should not be used for any purpose (including, without limitation, automotive, aerospace, medical, life-saving applications, or any other application which requires especially high reliability for the prevention of such defect as may directly cause damage to the third party's life, body or property) not expressly set forth in applicable AEM product documentation. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Warranties granted by AEM shall be deemed void for products used for any purpose not expressly set forth in applicable AEM product documentation. AEM shall not be liable for any claims or damages arising out of products used in applications not expressly intended by AEM as set forth in applicable AEM product documentation. The sale and use of AEM products is subject to AEM terms and conditions of sale. Please refer to AEM's website for updated catalog and terms and conditions of sale.